

AMENDMENTS TO THE CLAIMS:

The following listing of claims replaces all prior listings, and all prior versions, of claims in the application.

LISTING OF CLAIMS:

1. (Currently amended) A photosensitive resin composition comprising:

(A) a polymer having an acid functional group and/or a substituent derived therefrom;

(B) a compound represented by the general formula (10):



wherein X represents an n-valent organic group, n represents an integer of 2 to 6, and each of R₄ and R₅ represents hydrogen or a monovalent organic group, at least one of R₄ and R₅~~said monovalent organic group~~ is selected from the group consisting of:



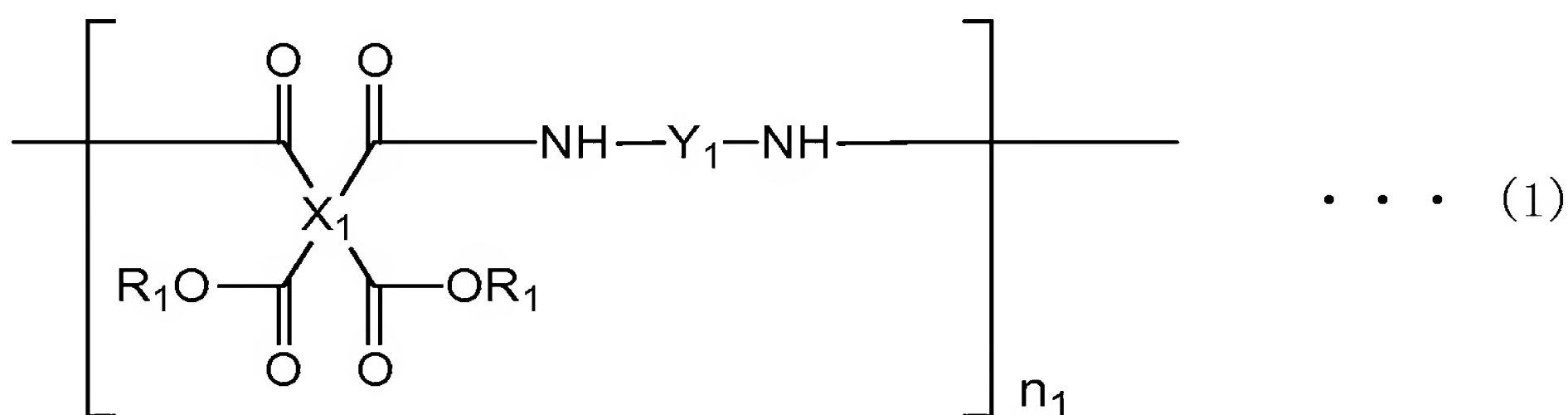
wherein R₃ represents a monovalent organic group; X₃ represents an oxygen, sulfur, or nitrogen atom; and n represents 1 when X₃ is an oxygen atom or a sulfur atom, or n represents 2 when X₃ is a nitrogen atom;

(C) a photoreactive compound; and

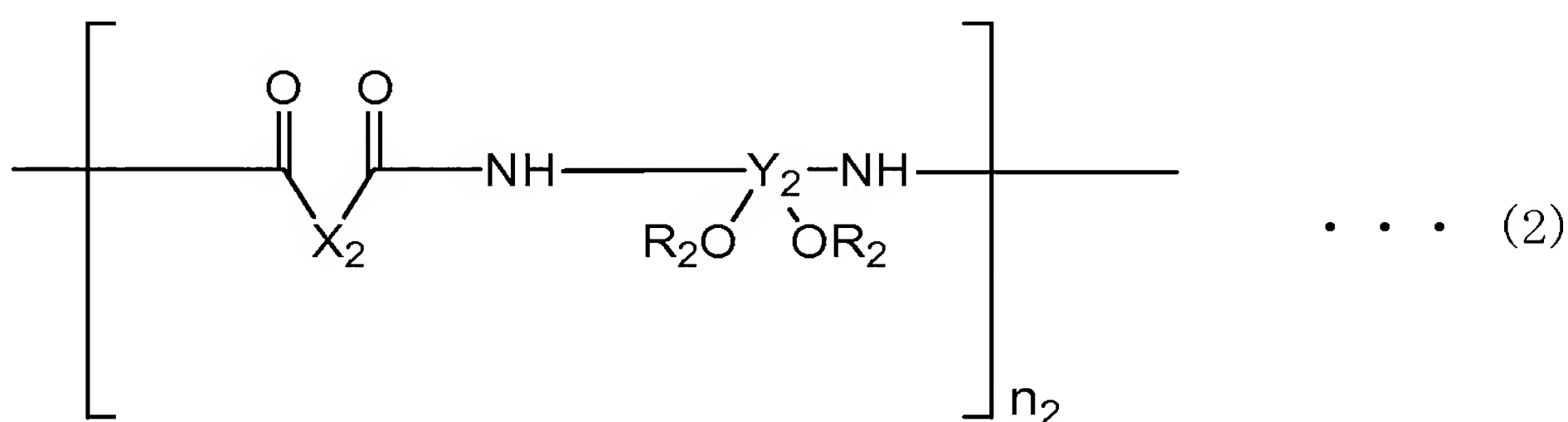
(D) a solvent,

wherein said polymer (A) is a heat-resistant polymer, and

wherein the heat-resistant polymer is a polyimide precursor represented by the general formula (1) below or polyimide derived from the precursor, a polybenzoxazole precursor represented by the general formula (2) below or polybenzoxazole derived from the precursor, a copolymer thereof, or a mixture thereof:



wherein X₁ represents a tetravalent organic group, Y₁ represents a divalent organic group, R₁ represents hydrogen or a monovalent organic group, and n₁ represents an integer of 2 to 500 corresponding to the number of the repeating units of the polymer,



wherein X₂ represents a divalent organic group, Y₂ represents a tetravalent organic group, of which two valences are used in bonding to hydroxyl groups, R₂ represents hydrogen or a monovalent organic group, and n₂ represents an integer of 2 to 500 corresponding to the number of the repeating units of the polymer
~~polyimide precursor, a polyimide, a polybenzoxazole precursor, a polybenzoxazole, a copolymer thereof, or a mixture thereof.~~

2. (Original) The photosensitive resin composition according to claim 1, wherein the compound of the component (B) further has at least one acid functional group and/or substituent derived therefrom.

3. and 4. (Cancelled).

5. (Currently amended) The photosensitive resin composition according to claim 1, ~~wherein the component (A) further has at least one substituent derived from an amine functional group in itself or in another component (A), and wherein the~~ component (B) further has at least one acid functional group and/or substituent derived therefrom.

6. (Currently amended) The photosensitive resin composition according to claim 5, ~~wherein the component (A) has one substituent derived from an amine functional group, and wherein the component (B) has one substituent or two~~ substituents derived from an amine functional group and has one acid functional group and/or substituent derived therefrom.

7. (Cancelled).

8. (Original) The photosensitive resin composition according to claim 1, wherein the acid functional group in the polymer (A) is a carboxyl group and/or a phenolic hydroxyl group.

9. (Cancelled).
10. (Original) A method for forming a pattern, comprising:
a step of applying the photosensitive resin composition according to claim 1 onto a substrate and drying it;
a step of subjecting the applied and dried photosensitive resin film to light exposure;
a step of subjecting the exposed photosensitive resin film to development using an alkaline aqueous solution; and
a step of subjecting the pattern obtained in the development to heat treatment.
11. (Original) An electronic part having an electronic device having the pattern obtained by the method according to claim 10, wherein the pattern is an interlayer dielectric layer and/or a surface protecting film layer.
12. (Cancelled).
13. (Previously presented) The photosensitive resin composition according to claim 1, wherein said R_3 is a monovalent organic group having 1 to 20 carbon atoms.
14. (Previously presented) The photosensitive resin composition according to claim 1, wherein said compound of the component (B) serves as a

chain extender capable of increasing molecular weight of said polymer of the component (A) during a heat treatment of the photosensitive resin composition.

15. (Previously presented) The photosensitive resin composition according to claim 1, which contains 0.05 to 50 parts by weight of said compound of the component (B) relative to 100 parts by weight of said polymer of the component (A).

16. (Previously presented) The photosensitive resin composition according to claim 1, which contains 0.2 to 20 parts by weight of said compound of the component (B) relative to 100 parts by weight of said polymer of the component (A).

17. (Previously presented) The photosensitive resin composition according to claim 1, wherein said polymer (A) has an acid functional group.

18. (Previously presented) The photosensitive resin composition according to claim 1, wherein R_3 is selected from the group consisting of methyl, ethyl, propyl, isopropyl, n-butyl, s-butyl, t-butyl, cyclopropenyl, cyclobutyl, cyclopentyl, cyclohexyl, cyclohexylmethyl, cyclohexenyl, norbornyl, norbornenyl, adamantyl, benzyl, p-nitrobenzyl, trifluoromethyl, methoxymethyl, ethoxyethyl, methoxymethyl, ethoxymethyl, methoxyethoxymethyl, benzoxyethyl, ethoxytetrahydropyranyl, tetrahydrofuranyl, 2-trimethylsilylethoxymethyl, trimethylsilyl, t-butyl dimethylsilyl, 3-oxocyclohexyl, 9-fluorenylmethyl, methylthiomethyl, phenyl, toluyl, xylyl, 9,10-dihydroanthranyl, trimethylphenyl,

pentamethylphenyl, biphenyl, terphenyl, quaterphenyl, dimethylbiphenyl, naphthalenyl, methylnaphthalenyl, fluorenyl, fluorophenyl, fluorobiphenyl, isopropylidenebiphenyl, tetrafluoroisopropylidenebiphenyl, benzyl phenyl ether, phenyl ether, phenoxytoluoyl, methoxybiphenyl, dimethoxybiphenyl, methoxynaphthalenyl, dimethoxynaphthalenyl, and nitrophenyl.